



MERCURY[®] MP

Advanced Automatic Batch Spray System

Automatic spray procedure for cleaning silicon wafers up to 8" in diameter. Suitable for pre-diffusion cleaning, stripping in ozonated water and etching in HF or BOE. Small compact dimensions. Fast processing of the procedure. Safe operation. Low consumption of chemicals, especially in combination with our ozone water generator.

Features and Benefits

- High wafer capacity
- Reduced DI water consumption
- Savings of Chemicals
- Low effluent and Disposal Costs
- High Process Reliability
- Small Footprint
- Safe operation
- Reliable operation

Configuration

- Six cassettes for 6" wafers (150 wafers) **
- Four cassettes for 8" wafers (100 wafers) **
- PLC controller
- 15" Touchscreen LCD Display
- PFA high purity pneumatic operated valve
- No metal contamination
- In-line ultrapure DI water heater
- Canister console
- Recirculation tank for HF / BOE
- Chamber Temperature Measurement

Process availability

- B clean
- C clean
- RCA clean
- SC1 clean
- SC2 clean
- Oxide etch
- Ozone clean
- Piranha clean
- Rinse and Dry

Optionals

- Computer network support
- SECSII/GEM support
- O3 water generator as H2SO4 alternative
- IR acid heater
- Remote control by Smartphone
- Compact one-piece version ***



* available as optional accessories

** depending on used turntable configuration

*** brand new model available since Q1 2014

SPRAY SYSTEM

Advanced All-in-one high capacity wet processing equipment ready for ozone water application

- Surface conditioning
- Ready for 8" wafers
- O3 water applicable *
- 6 chemical canisters
- Cost - Effective
- Safe & Reliable
- 15" Touchscreen LCD



Manufacturer of Equipment
for the Semiconductor Industry

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